STP12N65M2



N-channel 650 V, 0.42 Ω typ., 8 A MDmesh™ M2 Power MOSFET in a TO-220 package

Datasheet - production data

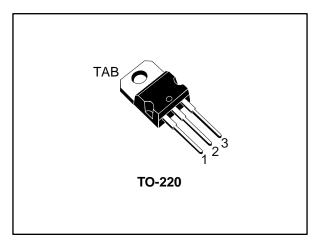
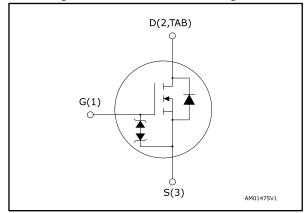


Figure 1: Internal schematic diagram



Features

Order code	V _{DS}	R _{DS(on)} max.	ΙD
STP12N65M2	650 V	0.50 Ω	8 A

- Extremely low gate charge
- Excellent output capacitance (C_{OSS}) profile
- 100% avalanche tested
- Zener-protected

Applications

• Switching applications

Description

This device is an N-channel Power MOSFET developed using MDmesh™ M2 technology. Thanks to its strip layout and an improved vertical structure, the device exhibits low on-resistance and optimized switching characteristics, rendering it suitable for the most demanding high efficiency converters.

Table 1: Device summary

Order code	Marking	Package	Packing
STP12N65M2	12N65M2	TO-220	Tube

Contents STP12N65M2

Contents

1	Electric	al ratings	3
		al characteristics	
	2.1	Electrical characteristics (curves)	6
3	Test cir	cuits	8
4	Packag	e information	9
	4.1	TO-220 type A package information	10
5	Revisio	n history	12

STP12N65M2 Electrical ratings

1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V _G s	Gate-source voltage	±25	V
I-	Drain current (continuous) at T _{case} = 25 °C	8	۸
l _D	Drain current (continuous) at T _{case} = 100 °C	5	Α
I _{DM} ⁽¹⁾	Drain current (pulsed)	32	Α
P _{TOT}	Total dissipation at T _{case} = 25 °C	85	W
dv/dt ⁽²⁾	Peak diode recovery voltage slope		V/ns
dv/dt ⁽³⁾	MOSFET dv/dt ruggedness		V/IIS
T _{stg}	Storage temperature range		°C
Tj	Operating junction temperature range -55 to 150		C

Notes:

Table 3: Thermal data

Symbol	Parameter	Value	Unit
R _{thj-case}	Thermal resistance junction-case	1.47	0000
R _{thj-amb}	Thermal resistance junction-ambient		°C/W

Table 4: Avalanche characteristics

Symbol	Parameter	Value	Unit
I _{AR}	Avalanche current, repetitive or non-repetitive (pulse width limited by $T_{j\text{max.}}$)	1.6	А
E _{AS}	Single pulse avalanche energy (starting $T_j = 25$ °C, $I_D = I_{AR}$, $V_{DD} = 50$ V)	250	mJ

 $^{^{\}left(1\right) }$ Pulse width is limited by safe operating area.

 $^{^{(2)}}$ I_{SD} \leq 8 A, di/dt = 400 A/ μ s, V_{DS(peak)} < V_{(BR)DSS}, V_{DD} = 400 V

 $^{^{(3)}}$ V_{DS} ≤ 520 V

Electrical characteristics STP12N65M2

2 Electrical characteristics

(T_{case} = 25 °C unless otherwise specified)

Table 5: Static

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	$V_{GS} = 0 \text{ V}, I_{D} = 1 \text{ mA}$	650			V
	Zaro goto voltago droin	$V_{GS} = 0 \text{ V}, V_{DS} = 650 \text{ V}$			1	
IDSS	Zero-gate voltage drain current	$V_{GS} = 0 \text{ V}, V_{DS} = 650 \text{ V},$ $T_{case} = 125 \text{ °C}^{(1)}$			100	μΑ
I _{GSS}	Gate-body leakage current	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			±10	μΑ
V _{GS(th)}	Gate threshold voltage	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	2	3	4	V
R _{DS(on)}	Static drain-source on-resistance	V _{GS} = 10 V, I _D = 4 A		0.42	0.50	Ω

Notes:

Table 6: Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
Ciss	Input capacitance		ı	535	ı	
Coss	Output capacitance	$V_{DS} = 100 \text{ V}, f = 1 \text{ MHz},$	ı	25	ı	pF
Crss	Reverse transfer capacitance	$V_{GS} = 0 V$	-	1.1	-	Pi
Coss eq. (1)	Equivalent output capacitance	V _{DS} = 0 to 520 V, V _{GS} = 0 V	1	144	1	pF
Rg	Intrinsic gate resistance	f = 1 MHz, I _D = 0 A	-	7	-	Ω
Q_g	Total gate charge	$V_{DD} = 520 \text{ V}, I_D = 8 \text{ A},$	ı	16.7	ı	
Q _{gs}	Gate-source charge	V _{GS} = 0 to 10 V (see Figure 15: "Test circuit	-	2.6	-	nC
Q_{gd}	Gate-drain charge	for gate charge behavior")	-	8.6	-	

Notes:

Table 7: Switching times

Table 11 Citite in ig times						
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)}	Turn-on delay time	V _{DD} = 325 V, I _D = 4 A	ı	9	ı	
tr	Rise time	R _G = 4.7 Ω , V _{GS} = 10 V (see Figure 14: "Test circuit for	ı	7	ı	
t _{d(off)}	Turn-off delay time	resistive load switching times"	1	34	ı	ns
t _f	Fall time	and Figure 19: "Switching time waveform")	-	13.5	-	

 $^{^{(1)}}$ Defined by design, not subject to production test.

 $^{^{(1)}}$ Coss eq. is defined as a constant equivalent capacitance giving the same charging time as Coss when VDS increases from 0 to 80% VDSS.

Table 8: Source-drain diode

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I _{SD} ⁽¹⁾	Source-drain current		-		8	Α
I _{SDM} ⁽²⁾	Source-drain current (pulsed)		-		32	Α
V _{SD} ⁽³⁾	Forward on voltage	V _{GS} = 0 V, I _{SD} = 8 A	-		1.6	V
t _{rr}	Reverse recovery time	$I_{SD} = 8 \text{ A, di/dt} = 100 \text{ A/}\mu\text{s,}$	-	313		ns
Qrr	Reverse recovery charge	V _{DD} = 60 V (see Figure 16: "Test circuit for	-	2.7		μC
I _{RRM}	Reverse recovery current	inductive load switching and diode recovery times")	-	17		А
t _{rr}	Reverse recovery time	$I_{SD} = 8 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s},$	-	462		ns
Qrr	Reverse recovery charge	$V_{DD} = 60 \text{ V}, T_j = 150 \text{ °C}$ (see Figure 16: "Test circuit for	-	4.1		μC
I _{RRM}	Reverse recovery current	inductive load switching and diode recovery times")	-	17.5		Α

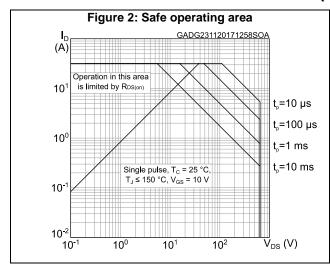
Notes:

⁽¹⁾Limited by package.

 $^{^{\}left(2\right) }$ Pulse width is limited by safe operating area.

 $^{^{(3)}}$ Pulse test: pulse duration = 300 μ s, duty cycle 1.5%.

2.1 Electrical characteristics (curves)



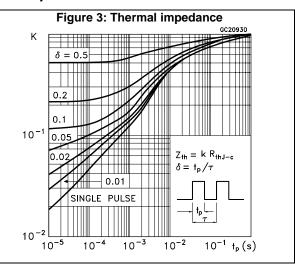
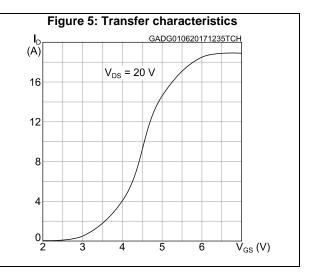
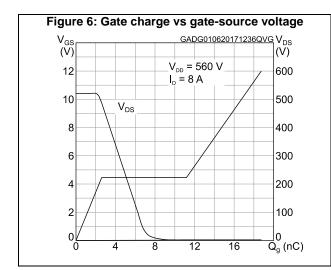
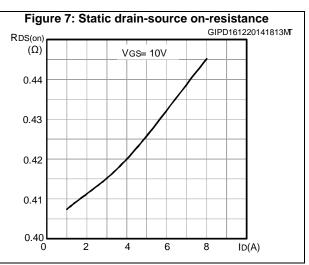


Figure 4: Output characteristics

(A) $V_{GS} = 7, 8, 9, 10 \text{ V}$ 16 $V_{GS} = 6 \text{ V}$ 12 $V_{GS} = 5 \text{ V}$ 10 $V_{GS} = 4 \text{ V}$ 11 $V_{GS} = 4 \text{ V}$ 12 $V_{GS} = 4 \text{ V}$ 13 $V_{GS} = 4 \text{ V}$ 14 $V_{GS} = 4 \text{ V}$ 15 $V_{GS} = 6 \text{ V}$







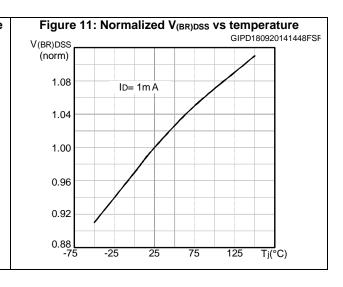
STP12N65M2 Electrical characteristics

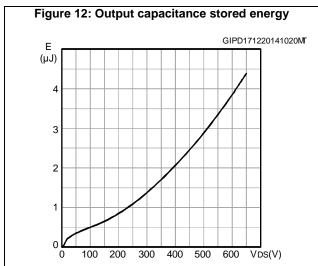
Figure 8: Capacitance variations

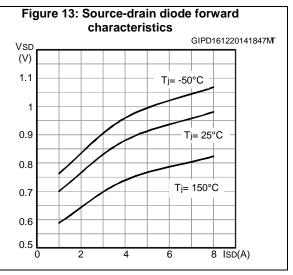
C
(pF)
1000
Ciss
Coss
10
10.1
1 10 100 VDS(V)

Figure 9: Normalized gate threshold voltage vs temperature GIPD180920141442FSF VGS(th) (norm) $ID = 250 \mu A$ 1.1 1.0 0.9 0.8 0.7 0.6 -75 -25 75 25 125 Tj(°C)

Figure 10: Normalized on-resistance vs temperature GIPD180920141459FSR R_{DS(on)} (norm) 2.2 1.8 V_{GS}= 10 V 1.4 1.0 0.6 0.2 T_J(°C) -25 25 -75 75 125







Test circuits STP12N65M2

behavior

I_G= CONST

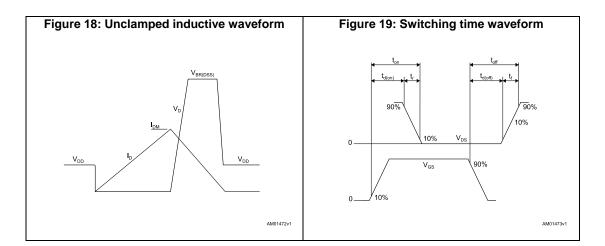
2.7 kΩ 47 kΩ 1 kΩ

⊥ 100 nF

3 **Test circuits**

Figure 14: Test circuit for resistive load Figure 15: Test circuit for gate charge switching times 2200 µF

Figure 16: Test circuit for inductive load Figure 17: Unclamped inductive load test switching and diode recovery times circuit AM01471v1



STP12N65M2 Package information

4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

4.1 TO-220 type A package information

Figure 20: TO-220 type A package outline

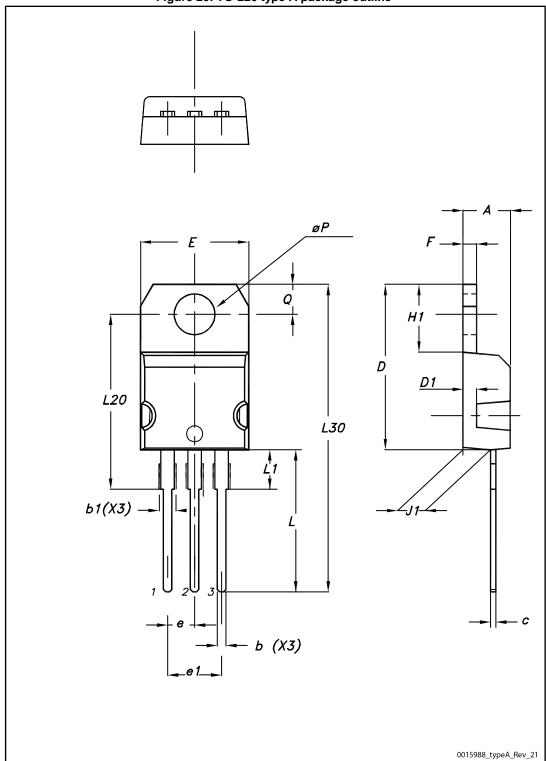


Table 9: TO-220 type A package mechanical data

Dim.	,	mm	
	Min.	Тур.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.55
С	0.48		0.70
D	15.25		15.75
D1		1.27	
Е	10.00		10.40
е	2.40	2.70	
e1	4.95		5.15
F	1.23 1.3		1.32
H1	6.20 6.		6.60
J1	2.40		2.72
L	13.00		14.00
L1	3.50		3.93
L20		16.40	
L30		28.90	
øΡ	3.75		3.85
Q	2.65		2.95

Revision history STP12N65M2

5 Revision history

Table 10: Document revision history

Date	Revision	Changes
28-Nov-2017	1	First release

IMPORTANT NOTICE - PLEASE READ CAREFULLY

STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2017 STMicroelectronics - All rights reserved



X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by STMicroelectronics manufacturer:

Other Similar products are found below:

614233C 648584F IRFD120 JANTX2N5237 FCA20N60_F109 FDZ595PZ 2SK2545(Q,T) 405094E 423220D TPCC8103,L1Q(CM MIC4420CM-TR VN1206L SBVS138LT1G 614234A 715780A NTNS3166NZT5G SSM6J414TU,LF(T 751625C BUK954R8-60E DMN3404LQ-7 NTE6400 SQJ402EP-T1-GE3 2SK2614(TE16L1,Q) 2N7002KW-FAI DMN1017UCP3-7 EFC2J004NUZTDG ECH8691-TL-W FCAB21350L1 P85W28HP2F-7071 DMN1053UCP4-7 NTE221 NTE2384 NTE2903 NTE2941 NTE2945 NTE2946 NTE2960 NTE2967 NTE2969 NTE2976 NTE455 NTE6400A NTE2910 NTE2916 NTE2956 NTE2911 DMN2080UCB4-7 TK10A80W,S4X(S SSM6P69NU,LF DMP22D4UFO-7B